ALD Process Monitoring for 3D Device Structures

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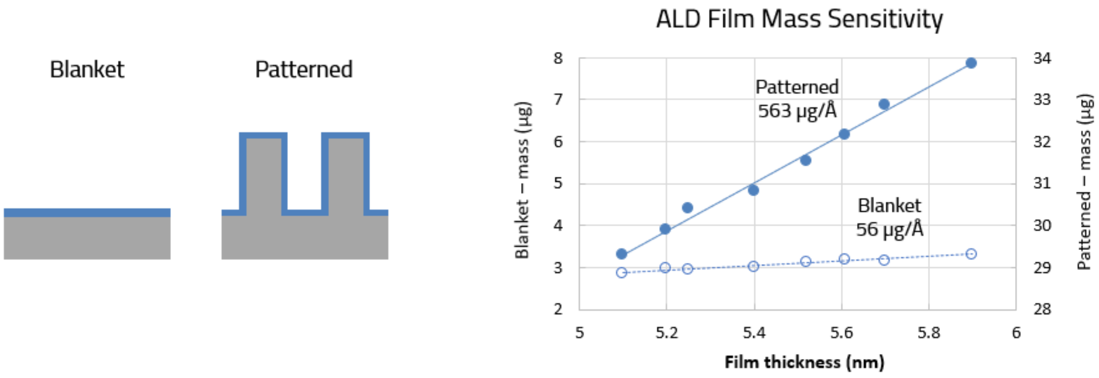

Fig 1. Comparison of Mass sensitivity to film on blanket and patterned wafers

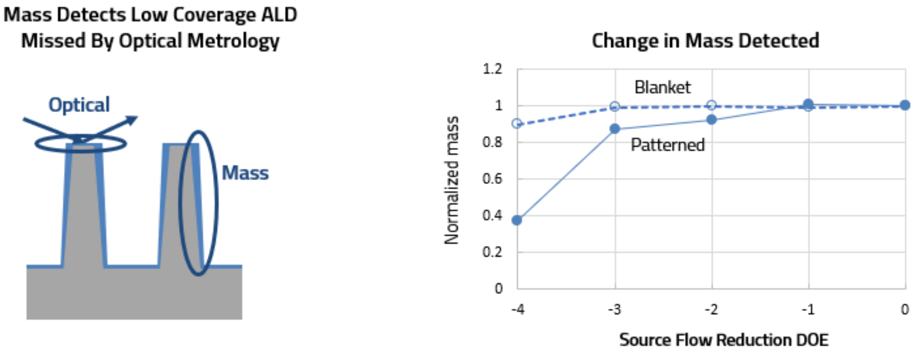

Fig 2. Comparison of Mass change from flow rate reduction on blanket and patterned wafers